

AMENDMENT UNDER 37 C.F.R. § 1.116

U.S. Application No. 09/664,094

Attorney Docket No. Q60884

sub
C17
B1
cmf.

2. (Twice Amended) A semiconductor integrated circuit comprising a signal transmission line patterns of a microstrip structure comprising of a signal line and a ground plate, wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole is not electrically connected to said signal line and said ground plate.

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C27

5. (Twice Amended) A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate, wherein at least one hole is formed in both of said signal line and said ground plate, and an inner wall of said hole is not electrically connected to said signal line and said ground plate.